

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

**(19) World Intellectual Property Organization
International Bureau**



**(43) International Publication Date
6 May 2005 (06.05.2005)**

PCT

(10) International Publication Number
WO 2005/041561 A1

(51) International Patent Classification⁷: H04N 5/225

(21) International Application Number: PCT/IB2004/052140

(22) International Filing Date: 19 October 2004 (19.10.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data: 03103980.3 27 October 2003 (27.10.2003) EP

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(81) **Designated States** (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM

AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

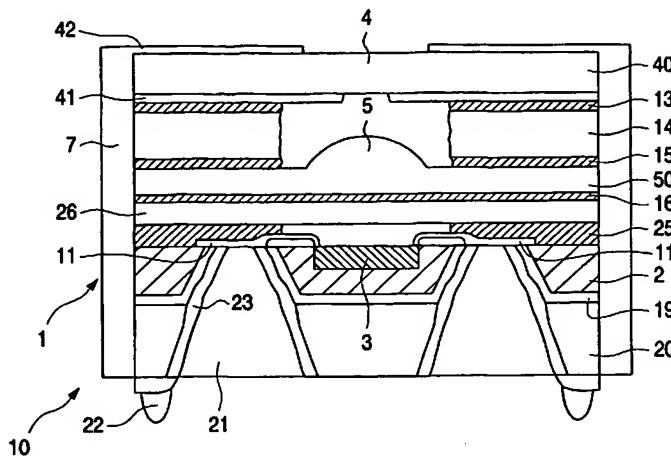
(84) **Designated States** (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declaration under Rule 4.17:

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(54) **Title:** CAMERA MODULE AND MANUFACTURING METHOD FOR SUCH A CAMERA MODULE



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(57) Abstract: The invention relates to a camera module (10) which comprises a semiconductor housing (1) that contains a solid-state image sensor (2) with a radiation-sensitive surface area (3), and an optical element (4) located above the solid-state sensor (2) and which forms a shield against laterally scattered radiation, comprising a disk-shaped body with a primary radiation-opaque area and a secondary radiation-transparent area located within the primary area, of which a surface close to the sensor (2) is smaller than a surface more remote from the sensor (2). According to the invention the optical element (4) comprises at least one plate (40) of transparent material of which two sides are covered with a radiation-opaque layer (41,42) which is provided with an aperture, in which the aperture in the layer (41) close to the sensor (2) has a smaller surface than the aperture in the layer (42) located remote from the sensor (2), and in which the primary and secondary areas are defined respectively by portions of the at least one plate (40) sandwiched between the opaque layers (41,42) and the apertures therein. Such a module (10) is particularly well-suited to wafer-scale manufacturing. The invention also comprises a method for manufacturing such a module (10).



MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)

Published:

— with international search report

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